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Please find below and/or attached an Office communication concerning this application or proceeding.



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Serial Number: 10/620714 Attorney's Docket #: 108298532US1

Filing Date: 7/15/2003;

Applicant: Corisis

Examiner: Alexander Williams

This application is a divisional application of serial number 09/644766, filed 8/23/2000, now U.S. Patent # 6,607,937.

Applicant's Amendment filed 7/1/05 to the Applicant's election of species of figure 3 (claims 50-55, 57-74, 76 and 77), filed 6/29/04, has been acknowledged.

This application contains claims 56, 75 and 78-83 drawn to an invention non-elected without traverse in Paper No. 4.

Claims 1-49 and 63 have been canceled.

Claim 77 is rejected under 35 U.S.C. § 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

In claim 77, In the phrase "further wherein all the conductive members extending away from **an encapsulant of the second microelectronic device**" the portion stating "**an encapsulant of the second microelectronic device**" has previously been mentioned. It should probably be —the encapsulant of the second microelectronic device--.

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

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(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 50 to 55, 57-59, 62, 64, 67-74, 76 and 77 are rejected under 35 U.S.C. 102(b) as being anticipated by Hernandez (U.S. Patent # 4,658,327).

50. Hernandez (figures 1 to 14) specifically figure 9A show a packaged microelectronic devices, comprising: a support member **54** having support member circuitry; a first packaged microelectronic device **52** connected to at least one of the support member and the support member circuitry and having a first microelectronic die (**inherit within 52**) generally encased in a first encapsulant (**outer encapsulation of 52**) to define a first package configuration; and a second packaged microelectronic device **56** connected to at least one of the support member and the support member circuitry with the first packaged microelectronic device positioned between the support member and the second packaged microelectronic device, the second packaged microelectronic device having a second microelectronic die (**within 56**) generally encased in a second encapsulant (**outer portion of 56**) to define a second package configuration different than the first package configuration, and wherein the second package microelectronic device is not fixedly attached to the first packaged microelectronic device.

51. The assembly of claim 50, Hernandez further comprising a conductive connecting member (**59s connected to 56**) connected directly between the second packaged

microelectronic device and the support member circuitry, at least a portion of the connecting member being positioned adjacent to an outer edge of the first packaged microelectronic device.

52. The assembly of claim 50, Hernandez show wherein the first packaged microelectronic device has a first edge and a second edge facing opposite the first edge and the second packaged microelectronic device has a third edge and a fourth edge facing opposite the third edge, and wherein the third edge of the second packaged microelectronic device extends outwardly beyond the first edge of the first packaged microelectronic device and the fourth edge of the second packaged microelectronic device extends outwardly beyond the second edge of the first packaged microelectronic device.

53. The assembly of claim 50, Hernandez show wherein the first packaged microelectronic device has a first planform shape in a plane generally parallel to a plane of the support member and the second packaged microelectronic device has a second planform shape in a plane generally parallel to the plane of the support member, and further wherein the second planform shape is more extensive in at least one direction generally parallel to the plane of the support member than is the first planform shape.

54. The assembly of claim 50, Hernandez show wherein the second packaged microelectronic device is spaced apart from the first packaged microelectronic device to define a gap between the packaged devices.

55. The assembly of claim 50, Hernandez show wherein the second packaged microelectronic device has a plurality of conductive members **(58s connected to 56)** electrically coupled to the second microelectronic die and extending away from the second encapsulant, further wherein all the conductive members extending away from the second encapsulant are attached directly between the second packaged microelectronic device and the support member circuitry without being attached to the first packaged microelectronic device.

57. Hernandez (figures 1 to 14) specifically figure 9A show an assembly of packaged microelectronic devices, comprising: a support member **54**; a first packaged microelectronic device **52** connected to the support member and having a first microelectronic die **(inherent within 52)** generally encased in a first encapsulant **(outer portion of 52)** to define a first planform shape; and a second packaged microelectronic device **56** connected to the support member with the first packaged microelectronic device positioned between the support member and the second packaged

microelectronic device, the second packaged microelectronic device having a second microelectronic die (**inherent within 56**) generally encased in a second encapsulant (**outer portion of 56**) to define a second planform shape different than the first planform shape.

58. The assembly of claim 57, Hernandez show wherein the support member **54** defines a support member plane and the first planform shape describes an area in a first plane generally parallel to the support member plane that is smaller than an area described by the second planform shape in a second plane generally parallel to the support member plane.

59. The assembly of claim 57, Hernandez further comprising a conductive connecting member (**58s connected to 56**) connected directly between the second packaged microelectronic device and the support member circuitry, at least a portion of the connecting member being positioned adjacent to the first packaged microelectronic device.

60. The assembly of claim 57, Hernandez show wherein the first packaged microelectronic device has a first edge and a second edge facing opposite the first edge and the second packaged microelectronic device has a third edge and a fourth edge facing opposite the third edge, and wherein the third edge of the second packaged microelectronic device extends outwardly beyond the first edge of the first packaged microelectronic device and the fourth edge of the second packaged microelectronic device extends outwardly beyond the second edge of the first packaged microelectronic device.

61. The assembly of claim 57, Hernandez show wherein the second packaged microelectronic device is spaced apart from the first packaged microelectronic device to define a gap between the packaged devices.

62. The assembly of claim 57, Hernandez show wherein the second packaged microelectronic device **56** has a plurality of conductive members (**58s connected to 56**) electrically coupled to the microelectronic substrate and extending away from the second encapsulant, further wherein all the conductive members extending away from the second encapsulant are attached directly between the second packaged microelectronic device and the support member circuitry.

65. Hernandez (figures 1 to 14) specifically figure 9A show an assembly of packaged microelectronic devices, comprising: a support member **54**; a first packaged microelectronic device **52** having a first microelectronic die (**inherent within 52**)

generally encased in a first encapsulant (**outer portion of 52**) and connected to the support member with a plurality of solder balls **59**; and a second packaged microelectronic device **56** having a second microelectronic die (**inherent within 56**) generally encased in a second encapsulant (**outer portion of 56**) and connected to the support member with a plurality of elongated connection members (**58s connected form 56**) extending from the second packaged microelectronic device around at least part of the first packaged microelectronic device and attached directly to the support member.

64. The assembly of claim 65, Hernandez show wherein the first packaged microelectronic device includes a first surface facing toward the support member, a second surface facing away from the support member and toward the second packaged microelectronic device, and a plurality of third surfaces between the first and second surfaces, further wherein the elongated connection members (**58s connected to 56**) are positioned adjacent to the third surfaces of the first packaged microelectronic device.

66. The assembly of claim 65, Hernandez show wherein the second package microelectronic device is spaced apart from the first packaged microelectronic device to define a gap between the packaged devices.

67. The assembly of claim 65, Hernandez show wherein the support member includes support member circuitry, and further wherein all the elongated connection members (**58s connected to 56**) of the second microelectronic device are attached directly to the support member circuitry.

68. Hernandez (figures 1 to 14) specifically figure 9A show an assembly of packaged microelectronic devices, comprising: a support member **54** having support member circuitry; a first packaged microelectronic device **52** electrically coupled directly to the support member circuitry; and a second packaged microelectronic device **56** electrically coupled directly to the support member circuitry without any direct electrical connections to the first packaged microelectronic device, the first packaged microelectronic device being positioned between the support member and the second packaged microelectronic device, the second packaged microelectronic device not being fixed attached to the first packaged microelectronic device.

69. The assembly of claim 68, Hernandez further comprising an elongated conductive connecting member (**58s connected to 56**) connected between the second packaged microelectronic device and the support member circuitry, at least a portion of the

connecting member being positioned adjacent to the first packaged microelectronic device.

70. The assembly of claim 68, Hernandez show wherein the first packaged microelectronic device has a first edge and a second edge facing opposite the first edge and the second packaged microelectronic device has a third edge and a fourth edge facing opposite the third edge, and wherein the third edge of the second packaged microelectronic device extends outwardly beyond the first edge of the first packaged microelectronic device and the fourth edge of the second packaged microelectronic device extends outwardly beyond the second edge of the first packaged microelectronic device.

71. The assembly of claim 68, Hernandez show wherein the second packaged microelectronic device is spaced apart from the first packaged microelectronic device to define a gap between the packaged devices.

72. The assembly of claim 68, Hernandez show wherein the first packaged microelectronic device is electrically coupled to the second packaged microelectronic device via the support member circuitry.

73. Hernandez (figures 1 to 14) specifically figure 9A show an assembly of packaged microelectronic devices, comprising: a support member **54** having support member circuitry; a first packaged microelectronic device **52** electrically coupled directly to the support member circuitry; and a second packaged microelectronic device **56** connected directly to the support member with the first packaged microelectronic device being positioned between the support member and the second packaged microelectronic device, the second packaged microelectronic device not being fixedly attached to the first packaged microelectronic device.

74. The assembly of claim 73, Hernandez show wherein the second packaged microelectronic device is spaced apart from the first packaged microelectronic device to define a gap between the first and second packaged microelectronic devices.

76. The assembly of claim 73, Hernandez show wherein the first packaged microelectronic device has a first edge and a second edge facing opposite the first edge and the second packaged microelectronic device has a third edge and a fourth edge facing opposite the third edge, and wherein the third edge of the second packaged microelectronic device extends outwardly beyond the first edge of the first packaged microelectronic device and the fourth edge of the second packaged microelectronic



device extends outwardly beyond the second' edge of the first packaged microelectronic device.

77. The assembly of claim 73, Hernandez show wherein the second packaged microelectronic device has a plurality of conductive members (**58s connected to 56**) electrically coupled to the microelectronic substrate and extending away from an encapsulant (**outer portion of 56**) of the second microelectronic device, further wherein all the conductive members extending away from an encapsulant (**outer portion of 56**) of the second microelectronic device are attached directly between the second packaged microelectronic device and the support member circuitry.

Claims 68, 69, 71-74 and 77 are rejected under 35 U.S.C. 102(e) as being anticipated by Nakamura et al. (U.S. Patent # 6,278,176 B1).

68. Nakamura et al. (figures 1 to 31) specifically figure 17 show an assembly of packaged microelectronic devices, comprising: a support member **14** having support member circuitry; a first packaged microelectronic device (**lower 1A**) electrically coupled directly to the support member circuitry; and a second packaged microelectronic device (**upper 1A**) electrically coupled directly to the support member circuitry without any direct electrical connections to the first packaged microelectronic device, the first packaged microelectronic device being positioned between the support member and the second packaged microelectronic device, the second packaged microelectronic device not being fixed attached to the first packaged microelectronic device.

69. The assembly of claim 68, Nakamura et al. further comprising an elongated conductive connecting member **5b** connected between the second packaged microelectronic device and the support member circuitry, at least a portion of the connecting member being positioned adjacent to the first packaged microelectronic device.

71. The assembly of claim 68, Nakamura et al. show wherein the second packaged microelectronic device is spaced apart from the first packaged microelectronic device to define a gap between the packaged devices.

72. The assembly of claim 68, Nakamura et al. show wherein the first packaged microelectronic device is electrically coupled to the second packaged microelectronic device via the support member circuitry.

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73. Nakamura et al. (figures 1 to 31) specifically figure 17 show an assembly of packaged microelectronic devices, comprising: a support member **14** having support member circuitry; a first packaged microelectronic device (**lower 1A**) electrically coupled directly to the support member circuitry; and a second packaged microelectronic device (**upper 1A**) connected directly to the support member with the first packaged microelectronic device being positioned between the support member and the second packaged microelectronic device, the second packaged microelectronic device not being fixedly attached to the first packaged microelectronic device.

74. The assembly of claim 73, Nakamura et al. show wherein the second packaged microelectronic device is spaced apart from the first packaged microelectronic device to define a gap between the first and second packaged microelectronic devices.

77. The assembly of claim 73, Karnezos et al. show wherein the second packaged microelectronic device has a plurality of conductive members **5b** electrically coupled to the microelectronic substrate and extending away from an encapsulant of the second microelectronic device, further wherein all the conductive members extending away from an encapsulant of the second microelectronic device are attached directly between the second packaged microelectronic device and the support member circuitry.

## Response

Applicant's arguments filed 7/1/05 have been fully considered, but are moot in view of the new grounds of rejections detailed above.

The listed references are cited as of interest to this application, but not applied at this time.

Field of Search	Date
U.S. Class and subclass: 257/686,685,777,723,737,734,738,778,779,772,666,673, 668,687,678	8/31/04 3/29/05 9/8/05
Other Documentation: foreign patents and literature in 257/686,685,777,723,737,734,738,778,779,772,666,673, 668,687,678	8/31/04 3/29/05 9/8/05
Electronic data base(s): U.S. Patents EAST	8/31/04 3/29/05 9/8/05

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Alexander O Williams whose telephone number is (571) 272 1924. The examiner can normally be reached on M-F 6:30-7:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nathan Flynn can be reached on (571) 272 1915. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

AOW  
9/8/05



Primary Patent Examiner  
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